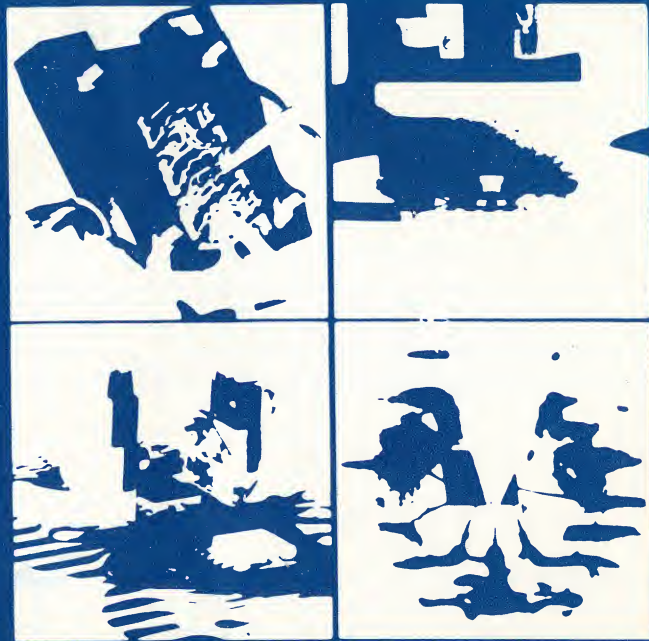


micro electronic packaging conference

NOV. 20-22, 1968 • RICKEYS HYATT HOUSE, PALO ALTO, CALIF.



The 1968 SAE Microelectronic Packaging Conference reviews the state of progress in manufacture and use of microelectronics.



Society of Automotive Engineers, Inc.

TWO PENNSYLVANIA PLAZA, NEW YORK, N. Y. 10001

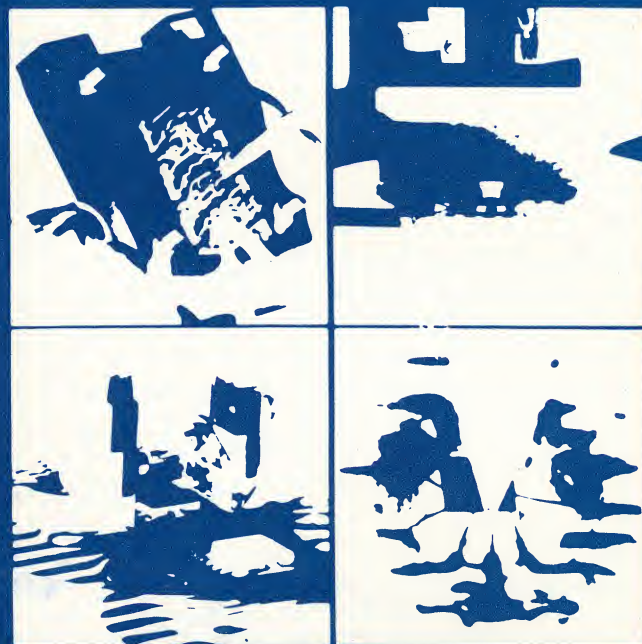
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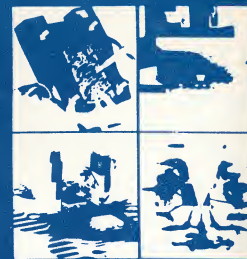
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F. B. Esty, President

M. J. Kittler, Treasurer

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micro electronic packaging conference



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November 20-22, 1968

Rickeys Hyatt House, Palo Alto, Calif.

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MAIL TO: Rickeys Hyatt House
4219 El Camino Real
Palo Alto, California 94306

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MAIL WITH CHECK TO:

Society of Automotive Engineers, Inc.
Two Pennsylvania Plaza
New York, New York 10001

Name (please print)

Company

Address

City State Zip

NOTE: Advance Registration Forms must be accompanied
by check and postmarked NO LATER THAN
Wednesday, October 30.

REGISTER ME FOR THE CONFERENCE AS FOLLOWS:

(Fee includes one copy of Proceedings)

☐ SAE Member or Enrolled Students* \$21.00

☐ Nonmember Guest \$36.00**

*SAE Members and Enrolled Students will be requested to
show Membership Cards.

**\$15.00 of the nonmember conference registration fee can
be credited toward SAE membership initiation fee if
application is made within six months.

Check enclosed, payable to SAE,
in the amount of \$.....

No refunds made after Wednesday, November 13, 1968.

HOTEL RESERVATION REQUEST FORM

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November 20-22, 1968

MAIL TO: Rickeys Hyatt House
4219 El Camino Real
Palo Alto, California 94306

Please reserve accommodations indicated below and confirm to:

Name (please print)

Address

City State Zip

GARDEN ROOMS

Single Rate \$14.00 ☐

Double Rate \$18.00 ☐

LAKE TOWER ROOMS

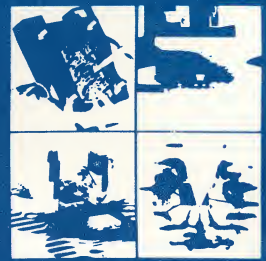
Single Rate \$16.00 ☐

Double Rate \$20.00 ☐

Arrival Nov. at a.m. Departure Nov. No. Persons

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and will be held until 6 p.m., unless later hour is specified.

micro electronic packaging conference



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